

REMARKS

Summary of the Office Action

Claims 1, 3-13, 16 and 17 stand rejected under 35 U.S.C. §103(a) as allegedly being unpatentable over Kodera et al. (US Pat. No. 6,195,149) in view of Hadoka et al. (JP 09-325328) and Shiraishi (US Pat. No. 6,864,947).

Summary of the Response to the Office Action

Claims 1, 3-13, 16 and 17 have been amended. No new matter has been entered. Claims 1, 3-13, 16 and 17 are pending in this application for further consideration.

All Claims Comply With §103

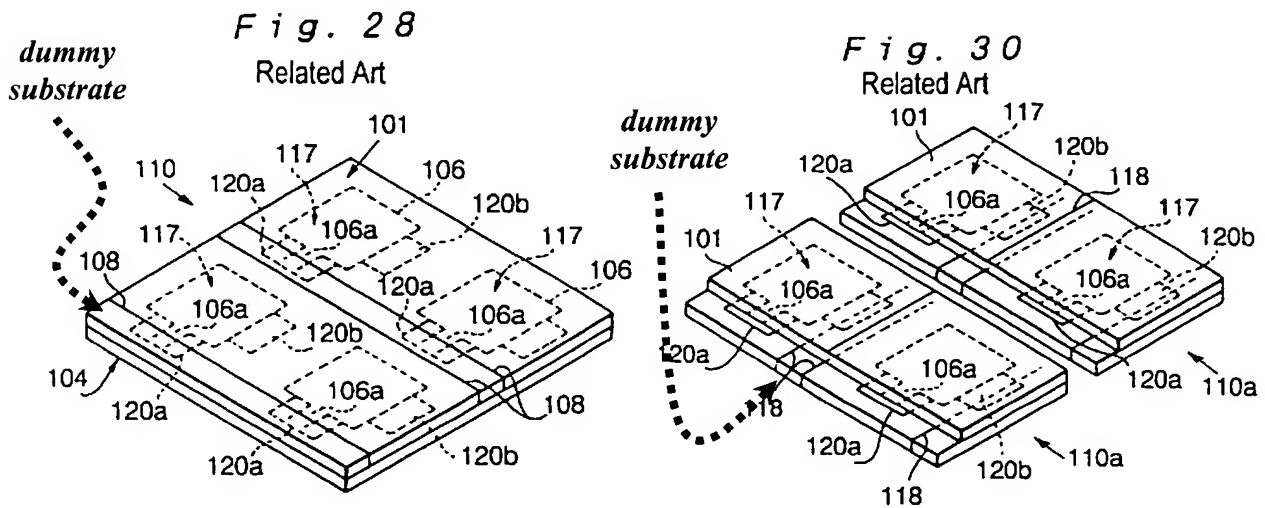
Claims 1, 3-13, 16 and 17 stand rejected under 35 U.S.C. §103(a) as allegedly being unpatentable over Kodera et al. in view of Hadoka et al. and Shiraishi. Applicants traverse the rejection as follows. As an initial matter, Applicants note that the Office Action is difficult to understand because all of the claims were grouped into one discussion even though each of the independent claims 1, 8, and 16, for example, recite different features. The rejection set forth in the Office Action is based on a combination of three references. However, it is not clear which one of the secondary references (i.e., Hadoka et al. and Shiraishi) is being relied upon to teach which missing feature from the primary reference (i.e., Kodera et al.) since all of the discussions are lumped together. Accordingly, the following response is based on Applicants' best understanding of the proffered rejection.

As amended, independent claim 1 recites, in part, “the *first and second mother substrates* include a plurality of dummy sections, *each dummy section* including *a main dummy portion* and *a secondary dummy portion*, and at least one of the sealant patterns under the first cutting lines binds the main dummy portions and secondary dummy portions together during the separating step (emphasis added).” Further, as amended, independent claim 8 recites, in part, “remnants of the separated mother substrates include *main dummy portions and secondary dummy portions divided by the first cutting lines therebetween*, and at least one of the sealant patterns is located underneath the first cutting lines such that at least one of the sealant patterns under the first cutting lines bind the main dummy portions and secondary dummy portions together during the separating step (emphasis added).” Similarly, as amended, independent claim 16 recites, in part, “remnants of the first and second substrates include *at least one main dummy portion and at least one secondary dummy portion divided by the first set of cutting lines therebetween*, and at least one of the sealant patterns under the first set of cutting lines binds the main dummy portion and secondary dummy portion together during the separating step (emphasis added).” Kodera et al., Hakoda et al., and Shiraishi, whether taken individually or in combination, fail to teach or even suggest at least these features.

The Office alleges that Kodera et al. teaches “a plurality of dummy glass substrates between the liquid crystal display panel units 117.” (OA: p. 4, para. 3.) The Office further alleges that Shiraishi teaches “a plurality of dummy glass substrates including main dummy glass substrates and second dummy glass substrates and at least one of the sealant patterns 21 (dummy

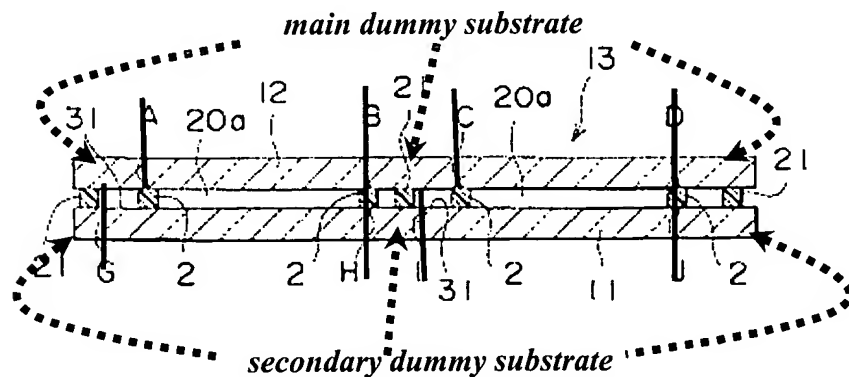
patters) under the cutting lines A-F binds the main dummy glass substrates and secondary dummy glass substrates together during the separating step.” (OA: p. 7, para. 3.) It appears that the rejection is based on the following figures of Kodera et al. and Shiraishi, as reproduced below, including the Office’s construction of the claimed features.

Kodera et al.



Shiraishi

FIG. 8B



As construed in the manner asserted by the Office, Kodera et al. and Shiraishi both fail to teach or suggest at least a “first and second mother substrates include a plurality of dummy sections, *each dummy section* including a main dummy portion and a secondary dummy portion (emphasis added)” as recited in claim 1, “remnants of the separated mother substrates include main dummy portions and secondary dummy portions *divided by the first cutting lines therebetween* (emphasis added)” as recited in claim 8, and “remnants of the first and second substrates include at least one main dummy portion and at least one secondary dummy portion *divided by the first set of cutting lines therebetween* (emphasis added)” as recited in claim 16. Hakoda et al. is silent as to generating dummy portions. Accordingly, Kodera et al., Hakoda et al., and Shiraishi, whether taken individually or in combination, fail to teach or suggest all the recited features of claims 1, 8, and 16 for at least the reasons stated above.

Applicants further note that Hakoda et al. is completely silent as to the steps of forming the first and second set of cutting lines. Accordingly, the cutting steps proffered in the Office Action (p. 6) are based on *pure speculation*, at best. As the proffered steps are neither explicit taught nor inherent to separating the LCD panels of Hakoda et al., Applicants respectfully submit that the proffered rejection is improper for at least this reason.

Due to their dependency to corresponding ones of independent claims 1, 8, and 16, claims 3-7, 9-13, and 17 are also allowable over Kodera et al., Hakoda et al., and Shiraishi for at least the reasons discussed above.

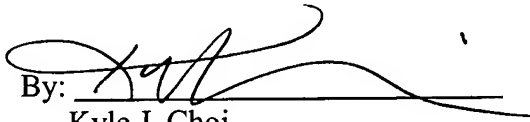
CONCLUSION

In view of the foregoing, Applicants respectfully request reconsideration and the timely allowance of the pending claims. Should the Examiner feel that there are any issues outstanding after consideration of the response, the Examiner is invited to contact the Applicants' undersigned representative to expedite prosecution.

If there are any other fees due in connection with the filing of this response, please charge the fees to our Deposit Account No. 50-0310. If a fee is required for an extension of time under 37 C.F.R. § 1.136 not accounted for above, such an extension is requested and the fee should also be charged to our Deposit Account.

Respectfully submitted,
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